



<b>Form Type</b>	Distribute	<b>Version</b>	2.0	<b>Ref</b>	IPC 1752A	<b>Sectionals</b>	Manufacturing Info/ Material Info	<b>Subsectionals</b>	D, A
<b>Supplier Information</b>									
<b>Company Name</b>	TE Connectivity	<b>Request Document ID</b>		<b>Contact Name</b>	Wu, Cc	<b>Contact Title</b>	Prod Compliance Engineer, China CIS Compliance		
<b>Company Unique ID</b>	TE Connectivity	<b>Response Date</b>	2016-02-26	<b>Contact Email</b>	cc.wu@te.com				
<b>Contact Phone Number</b>	86-21-33259321								
<b>Legal Statement</b>									
<b>Supplier Acceptance</b>	true								
<b>Legal Statement</b>									
The information provided in this document is based upon reasonable inquiry of our suppliers. This information is subject to change. This information does not in any way modify existing purchase specifications or existing contractual or other agreements terms between TE Connectivity (or its affiliated companies) and its customers.									
<b>Product</b>									
<b>Manufacturer Item number</b>	770967-1	<b>Amount</b>	2059.672	<b>Version</b>	-	<b>Identity</b>			
<b>Manufacturer Item Name</b>	03P MINI UMNL R/A HDR ASSY SN	<b>Weight Uom</b>	mg	<b>Mfr Site</b>		<b>Authority</b>			
<b>Date</b>		<b>UOM</b>	Each						
<b>EUROHS-0508</b>	Product(s) does not meet EU RoHS requirements and is not under exemptions								
<b>ChinaRoHS-0508</b>	Product(s) is NOT eligible for marking with the e code under China's Measures for Administration of the control of pollution by Electronic Information Products								
<b>EUREACH-0615</b>	REACH Candidate Substances of Very High Concern ARE NOT Yet Reviewed								
<b>Manufacturing Information</b>									
<b>J-STD-020 MSL Rating</b>		<b>Max Total a Wave Time</b>		<b>Ramp Rate</b>		<b>Wave Additional Info</b>			
<b>Classification Temp</b>		<b>Max Wave Solder Time</b>	0.0	<b>Ramp Down Rate</b>		<b>Psi Rating Reflow</b>			
<b>Max Time Within 5</b>		<b>Psi Rating Wave</b>		<b>Package Designator</b>		<b>Size</b>	0.0		
<b>Time Above 217</b>		<b>Reflow Additional Info</b>		<b>Preheat Max Temp</b>		<b>Terminal Base Alloy</b>	NAC		
<b>Preheat Duration</b>		<b>bulk Solder Termination</b>	NAC	<b>Nbr or Reflow Cycles</b>		<b>Terminal Plating</b>	NAC		
<b>Preheat Min Temp</b>		<b>Nbr of Instances</b>	0	<b>Component Temp Spike</b>		<b>Shape</b>	NAC		
<b>Product Disclosure</b>									
<b>Sub-Item/Material/Substance</b>	<b>Level</b>	<b>Name</b>	<b>Substance Category</b>	<b>Substance CAS</b>	<b>Substance Concentration</b>	<b>Quantity</b>	<b>Mass per Unit</b>	<b>UOM</b>	<b>Exemption</b>
Sub-Item	1	MINI UMNL BAND/PIN CONTACT				3.0	133.224	mg	
Material	2	Brass Wire				3.0	130.2	mg	
Substance	3	Copper	Supplier	7440-50-8	71.5	3.0	93.093	mg	
Substance	3	Beryllium	Supplier	7440-41-7	0.0010	3.0	0.001302	mg	
Substance	3	Zinc	Supplier	7440-66-6	28.0226	3.0	36.48543	mg	
Substance	3	Manganese	Supplier	7439-96-5	0.05	3.0	0.0651	mg	
Substance	3	Chromium	Supplier	7440-47-3	0.0010	3.0	0.001302	mg	
Substance	3	Iron	Supplier	7439-89-6	0.05	3.0	0.0651	mg	
Substance	3	Cobalt	Supplier	7440-48-4	0.1	3.0	0.1302	mg	
Substance	3	Arsenic	Supplier	7440-38-2	0.0099	3.0	0.0128898	mg	
Substance	3	Antimony	Supplier	7440-36-0	0.01	3.0	0.01302	mg	
Substance	3	Lead	Lead/Lead Compounds	7439-92-1	0.05	3.0	0.0651	mg	
Substance	3	Cadmium	Cadmium/Cadmium Compounds	7440-43-9	0.0050	3.0	0.00651	mg	
Substance	3	Mercury	Mercury/Mercury Compounds	7439-97-6	5.0E-4	3.0	6.51E-4	mg	
Substance	3	Nickel	Nickel	7440-02-0	0.2	3.0	0.2604	mg	
Material	2	Nickel Plate				3.0	0.761	mg	
Substance	3	Contains No Reportable TE5081-2 Substances	Supplier	TE5081-2-1212	0.2	3.0	0.001522	mg	
Substance	3	Lead	Lead/Lead Compounds	7439-92-1	0.1	3.0	7.61E-4	mg	
Substance	3	Nickel	Nickel	7440-02-0	99.7	3.0	0.75872	mg	

Material	2	Tin-Lead Plate				3.0	2.263	mg	
Substance	3	Tin	Supplier	7440-31-5	86.5	3.0	1.95749	mg	
Substance	3	Contains No Reportable TE5081-2 Substances	Supplier	TE5081-2-1212	0.5	3.0	0.011315	mg	
Substance	3	Lead	Lead/Lead Compounds	7439-92-1	13.0	3.0	0.29419	mg	
Sub-Item	1	03P MINI UMNL RT ANG HDR HSG				1.0	1660.0	mg	
Material	2	PA				1.0	1660.0	mg	
Substance	3	Water	Supplier	7732-18-5	0.3262	1.0	5.41492	mg	
Substance	3	2H-Azepin-2-one, hexahydro-	Supplier	105-60-2	0.4637	1.0	7.69742	mg	
Substance	3	Siloxanes and Silicones, di-Me	Supplier	63148-62-9	3.0E-4	1.0	0.00498	mg	
Substance	3	Poly[imino(1,6-dioxo-1,6-hexanediy)imino-1,6-hexanediy]	Supplier	32131-17-2	0.9451	1.0	15.68866	mg	
Substance	3	Benzenepropamide, N,N-1,6-hexanediybis[3,5-bis(1,1-dimethylethyl)-4-hydroxy-	Supplier	23128-74-7	0.4004	1.0	6.64664	mg	
Substance	3	1,2-Ethanediamine	Supplier	107-15-3	0.0033	1.0	0.05478	mg	
Substance	3	Phosphoric acid, sodium salt, hydrate (1:2:12)	Supplier	10039-32-4	0.025	1.0	0.415	mg	
Substance	3	Octadecanoic acid, calcium salt (2:1)	Supplier	1592-23-0	0.2012	1.0	3.33992	mg	
Substance	3	Octadecanamide, N,N-1,2-ethanediybis-	Supplier	110-30-5	0.1901	1.0	3.15566	mg	
Substance	3	1,3,5-Triazine-2,4,6(1H,3H,5H)-trione, compd. with 1,3,5-triazine-2,4,6-triamine (1:1)	Supplier	37640-57-6	9.0717	1.0	150.59022	mg	
Substance	3	Hexanedioic acid, polymer with hexahydro-2H-azepin-2-one and 1,6-hexanediamine	Supplier	24993-04-2	88.373	1.0	1466.9918	mg	